

ABSTRACT

In an electronic component comprising a semiconductor chip packaged in a molded part from which the lead terminals of the semiconductor chip project, a main cutting notch is formed on the obverse surface of each lead terminal before molding the molded part while leaving unnotched portions adjoining both ends of the main notch. Then, each lead terminal is cut at the main notch after molding the molded part, thereby making fewer and smaller cutting burrs occurring at the cut faces.